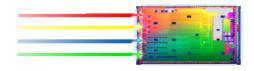


5th International Symposium for Optical Interconnect in Data Centres

Date: 19th September 2017

Location: Meeting Room J2, ECOC Exhibition 2017

FIBER TO THE CHIP





Luxtera Company Introduction



- Founded in 2001, Luxtera has the world's first Silicon Photonics platform proven in volume transceiver production
- In continuous production since 2009, > 1Mu transceivers deployed
- Strong demand for Luxtera's 100G products: Cloud Operators require costeffective 100G Single Mode Optics at high volume







- Shipments of new 100G products started in Q1 2016, with now more than 300k units deployed leading the market on price/performance and availability. Scaling production of new 100G optics products (1M units/year)
- Continuing R&D Investment: Roadmap supports 5 year hyper-growth cycle of 25/50/100/400G SMF transceivers leading to broad scale SoC integration.

Photonic Interposers For ASIC/SoC

Luxtera's Silicon Photonics

Fabless approach leveraging semi-conductor technology

- Commercial semiconductor fabs
- Commercial OSAT for assembly and test

Advanced photonic device libraries are a must

- State-of-the-art transceiver performance is required
- Many opportunities for improvement still to be explored

In-house electronic and photonic circuit design

- Co-design of electronics and photonics within a common EDA-environment
- Silicon Photonics allows new architectures and high level of integration

Reliable and stable light source

- Micro-packed laser diode or remote light source

Silicon Photonics Wafer Manufacturing

Fabless approach leveraging IC technology

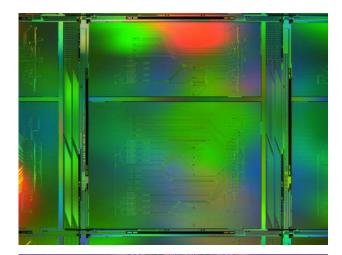
- No "boutique" processes
- Commercial fabs & OSAT for assembly and test
- Over its history Luxtera worked with 3 fabs for silicon photonics wafer manufacturing. March 2017 announcement: Luxtera works with TSMC on developing a 300 mm silicon photonics process

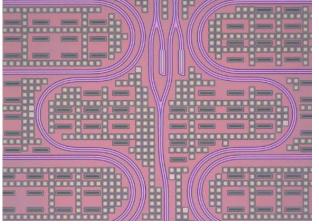
Silicon photonics wafer yields are usually very high

- Capable processes and tool sets in commercial fabs
- Capable process monitors
- Low density of photonic circuits

Process Design Kit (PDK) allows IC design approach

- Device Library p-cells w/behavioral models based on measured performance
- DRM/DRC Deck
- LVS & Parasitic extraction
- Co-simulation photonics + electronics





Silicon Photonics Device Libary

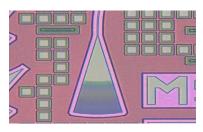
Advanced photonic device libraries are a must

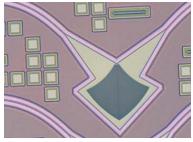
State-of-the-art transceiver performance is required, scaling to higher data rates requires:

- Higher signal to noise ratio: lower losses, higher modulation efficiency, higher detector responsivity
 - o Losses of coupling in and out of the Si Photonics chip are one of the major challenges
- Higher bandwidth modulators
- Higher bandwidth photodetectors

Developing design devices in TSMC process

- Advanced process:
 - o Enhanced device performance
 - Process capabilities allow broader design space for photonic devices
- Streamlined supply chain:
 - o Electronic and Photonic ICs
 - TSV capability





Integration Photonics & Electronics

Luxtera commercialized both, each approach has merits, we opted for hybrid integration going forward:

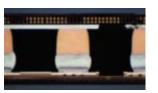
- Scalability
- Product and development cost
- Business/Supply chain considerations

Monolithic Integration (4x14 Gbps IC)

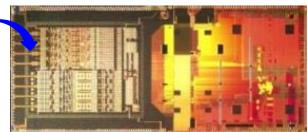
Hybrid Integration (4x28 Gbps ICs)



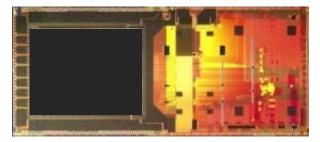
Electronic IC



Micro-bumps



Photonic IC

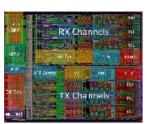


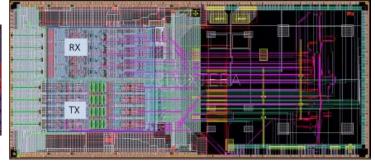
In-house electronic and photonic circuit design

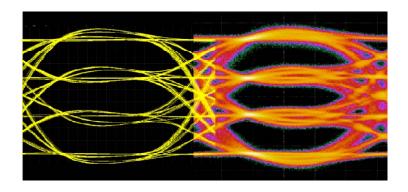
Co-design of electronics and photonics within a common EDA-environment

System level simulation using behavioral models & parasitics of photonic devices and interconnects

TX output 26 GB PAM-4, simulation vs actual:







• Silicon Photonics allows new architectures and high levels of integration

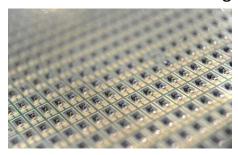
Light Source Integration

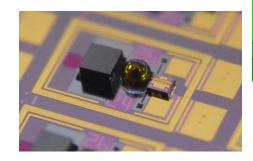
Reliable and stable light source

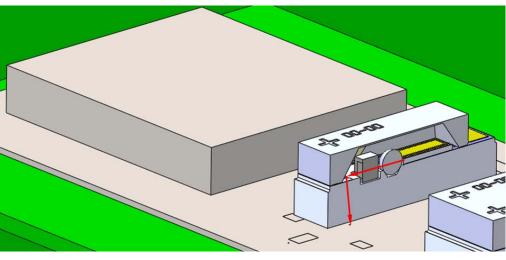
- Micro-packed InP laser diode for pluggable modules (require co-packaging)
- Remote light source for highly integrated and dense systems decouples light source and transceiver functions, e.g. ASIC integration (High T, serviceability, yield,...)

Conventional InP laser diode in silicon micro-package:

- Mature InP laser diode technology
- Faraday rotator as optical isolator for laser stability
- Efficient coupling scheme
- Delivered to module assembly line as known good light source
- Wafer level manufacturing:





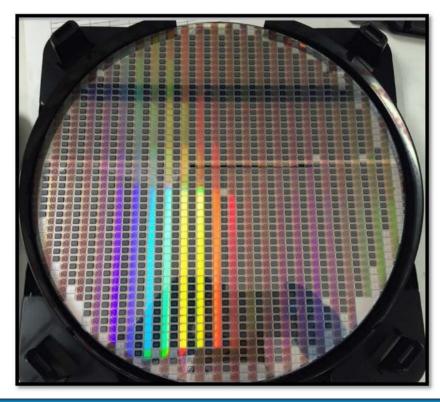


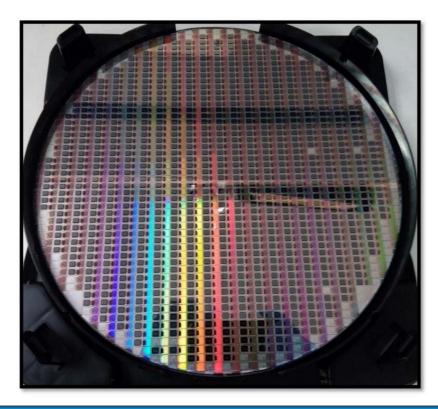
- High wall-plug efficiency:
 - > 15% (incl. coupling efficiency LD to Si P IC)
 - Single light source for 8 channels 25 Gbps (PSM-4)

Wafer Level Optical Assembly of Electronics and Photonics

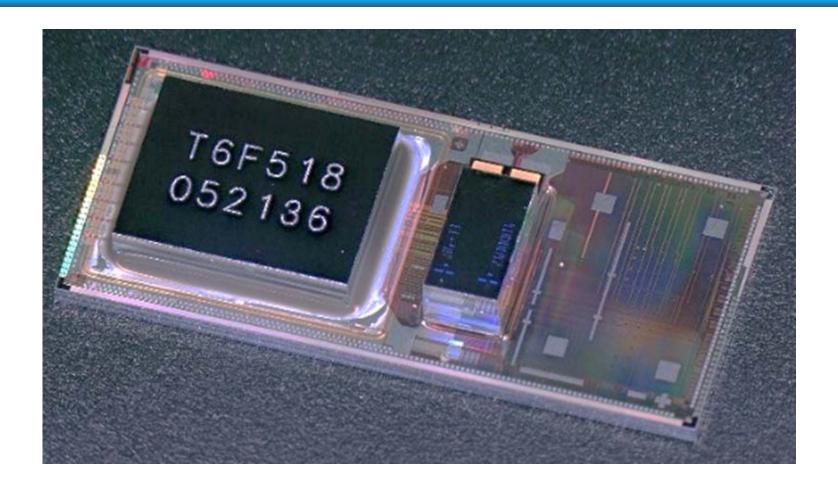
Electronic IC to Photonic IC

Light Source to Photonic IC

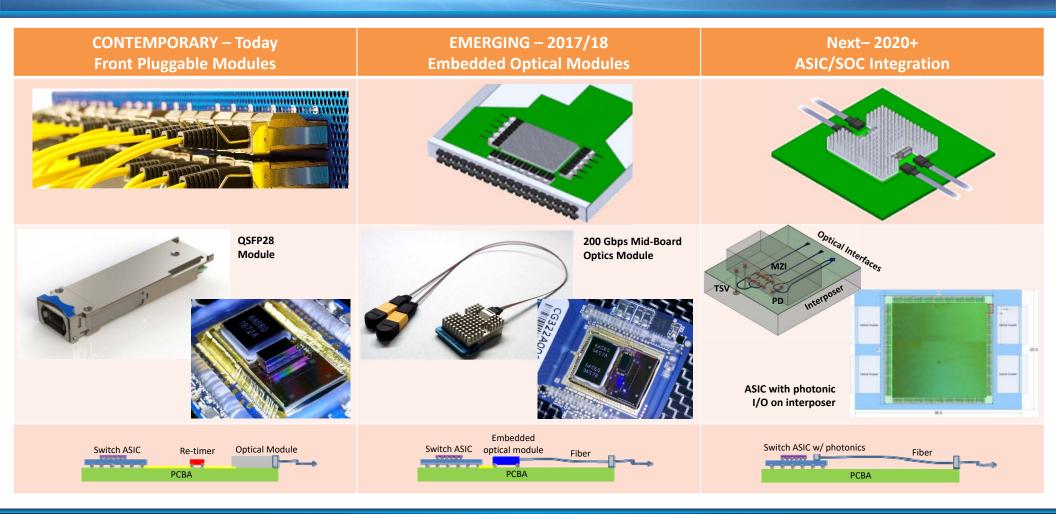




Silicon Photonics Optical Engine (100G TX+RX PSM-4)



High-Speed Interconnect Implementations & Form Factors



Silicon Photonics is the winning technology for DC interconnect

Scales in Performance

- Advanced photonic device libraries allow link margin and performance needed for ever increasing data rates
- Latest CMOS technology nodes for electronic circuits required for electronic functions (28 nm, 7 nm)
- Density scaling in multiple dimensions: data rate, modulation, wavelength, spatial
- Enables SoC integration with ASICs:
 - Very large scale integration of hundreds of transceivers on a single device
 - Very harsh (hot) environment -> remote III-V light source

Scales in Manufacturing

- Leverages semiconductor industry manufacturing infrastructure (fabless)
- Leverages semiconductor technology roadmap
- OSAT for Wafer Test & Assembly
- DFM, DFT, DFR
- Simplified and highly automated optical assembly



Acknowledgement:

This presentation contains work of the entire Luxtera team and its past and present technology partners, their contributions are greatly acknowledged.

Thank you for your interest.

Luxtera Proprietary

www.luxtera.com